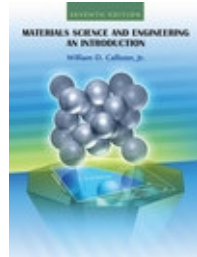


## EGN 3365 Materials Engineering



**Lecturer: Dr. Chunlei Wang**

Chapter 1 - 1



## EGN 3365 MATERIALS ENGINEERING

### Course Objective...

Learn the materials behavior and function through their internal structures.

### You will learn about:

- internal structure of the materials
- their corresponding properties
- how processing can change structure
- applications in engineering

### This course will help you to:

- use materials properly
- realize new design opportunities with materials

Chapter 1 - 2



## COURSE WEBSITES

<http://web.eng.fiu.edu/wangc/EGN3365.htm>

**Text Website:** <http://www.wiley.com/college/callister>

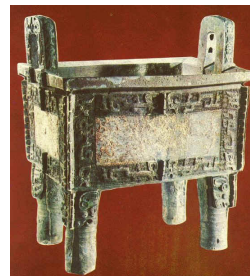
- Additional Chapters (Chapters 19-23)
- Complete solutions to selected problems
- Links to other web resources
- Extended learning objectives
- Self-assessment exercises

Chapter 1 - 3



## Chapter 1 - Introduction

- What is **materials science** and **materials engineering**?
- Why should we know about it?
- Materials drive our society
  - **Stone Age**
  - **Bronze Age**
  - **Iron Age**
  - **Now?**
    - **Silicon Age?**
    - **Polymer Age?**



Simuwu Ding, Shang Dynasty, China.  
 Dated to: 1400-1100 B.C.  
 Cu: 84.77, Sn: 11.44, Pb: 2.76 others:  
 0.9.  
 H x L x W (cm): 133.2 x 110 x 78  
 Weight: 875 kg

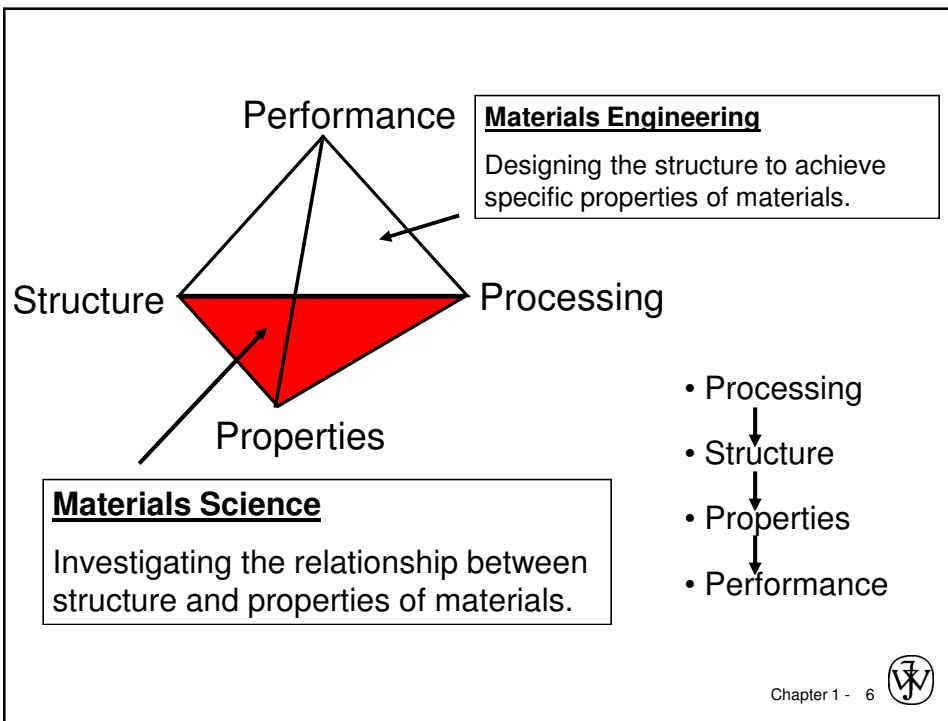
Chapter 1 - 4



## Brief Historical Overview

- **Paleolithic** (40,000 to 100,000 yrs ago): Stone tools and clay pots
- **Mesolithic** (10,000 to 40,000 yrs ago): Extensive use of stone tools and clay, stone statues, ochre (pigment)
- **Copper Age** (5,000 to 10,000 yrs ago): Copper ornaments, earthenware, metal smelting
- **Bronze Age** (3,000 to 5,000 yrs ago): Bronze (Cu/Sn), glass, iron smelting
- **Iron Age** (1000 – 3000 yrs ago): Carburized Iron, improved forging, porcelain
- **Steel and concrete** (100 – 1000 yrs ago)
- **Polymers** (beginning early 1900s)
- **Silicon** (60s – )
- **The present:** Age of biomaterials and nanomaterials?

Chapter 1 - 5



Chapter 1 - 6



## Classification of Materials

### Metals:

Elemental metal (iron, copper etc), steel, Alloys, Intermetallic compounds

### Ceramics:

Structural Ceramics (high-temperature load bearing), Refractories (corrosion-resistant, insulating), Whitewares (e.g. porcelains), Glass, Electrical Ceramics (capacitors, Insulators, transducers, etc.), Chemically Bonded Ceramics (e.g. cement and concrete)...

### Polymers:

Plastics, Adhesives, liquid crystals...

**Semiconductors:** Group IV elements (Si, Ge...), III-V (GaAs, InP...) , II-VI (CdSe, ZnS...), IV-VI (PbS, PbSe...)...

### Composites:

Particulate composites, (small particles embedded in a different material), Laminate composites (golf club shafts, tennis rackets, Damascus sword blades), Fiber reinforced composites (e.g. fiberglass)

### Biomaterials

### Nanoscale materials

Chapter 1 - 7



## Engineering Materials:

### Controlling Processing - Structure - Properties - Performance

#### • Realistic engineering materials:

##### Trade-off between

- properties (what do we need or want?)
- deterioration (how long will it last?)
- cost (what's the biggest bang for the buck?)
- Resources depletion (how to find new reserves, develop new environmentally-friendly materials, and increase recycling)

#### • How do you decide what materials to use?

- Pick Your Application  $\Rightarrow$  Required Properties  
(mechanical, electrical, thermal, magnetic, optical, deteriorative)
- Properties  $\Rightarrow$  Required Materials (type, structure, composition)
- Material  $\Rightarrow$  Required Processing (changes to structure and desired shape via casting, annealing, joining, sintering, mechanical, ...)

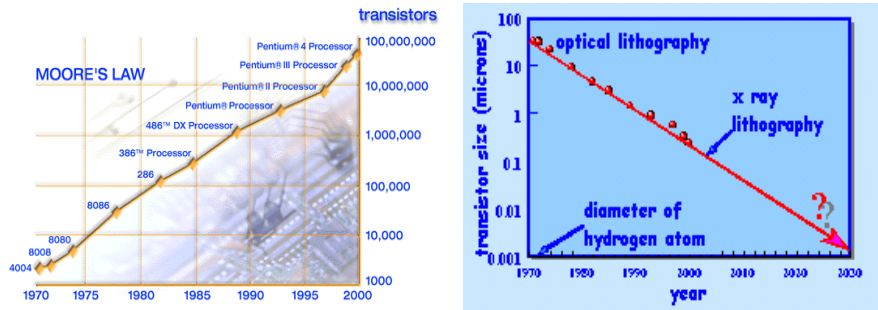
Chapter 1 - 8



## Needs for Materials (i.e. Final Performance)

- Microelectronics: **ICs, packaging, photoresists...**
  - Infrastructure: **Concrete, metal beams...**
  - Environmental control: **biodegradable polymers, ion exchange...**
  - Communication/Information: **fiber optics, LEDs...**
  - Energy: **solar cells, Li ion batteries, fuel cells...**
  - Automotive: **chassis, engine parts...**
  - Defense: **night vision, light weight/high strength composites for aircrafts...**
  - Biotechnology: **medical implants, biocompatible polymers, biosensors...**
  - Sporting goods: **bicycle frames, golf clubs...**
  - Homeland Security: **Sensor materials for explosive and biohazards...**
- and more... (no engineering without materials).**

## New Needs for “Future” Materials: an example



Pentium 4 Processor has 42,000,000 transistors!

DRAM half-pitch of 35 nm will be needed by 2014.

[Nanoscale materials and molecular electronics?](#)

To achieve **performance** needs, an understanding of materials' **properties** is necessary!

## Properties of Materials

	Stimulus	Response (e.g.)
Mechanical	<b>Applied load</b>	<b>Deformation</b>
Electrical	<b>Electric field</b>	<b>Electrical conduction</b>
Magnetic	<b>Magnetic field</b>	<b>Magnetization</b>
Thermal	<b>Heat</b>	<b>Heat conduction</b>
Optical	<b>Light</b>	<b>Reflection, absorption</b>
Deterioration ( <b>Chemical</b> )	<b>Chemicals</b>	<b>Oxidation, corrosion</b>

many materials needs combine different properties (e.g. piezoelectric materials).

**Characterization methods:** microscopy (optical, SEM, TEM, STM, AFM...), spectroscopy (uv-vis, FTIR...), crystallography, light scattering, mechanical testing, etc...

To obtain desired **properties**, the material must have the appropriate **structure**.

Chapter 1 - 11



## Structure

- **Types of atoms.**
- **Arrangement of atoms/molecules.**
  - e.g. **crystal structure, polymer chain length, crosslinking...**
- **Defects and impurities.**
- **Grain size.**
- **Etc...**

Structure at different length scales:

<u>Structural feature</u>	<u>Dimension (m)</u>
atomic bonding	~ $10^{-10}$
missing/extra atoms	$10^{-10}$
crystals (ordered atoms)	$10^{-8}$ - $10^{-1}$
second phase particles	$10^{-8}$ - $10^{-4}$
crystal texturing	> $10^{-6}$

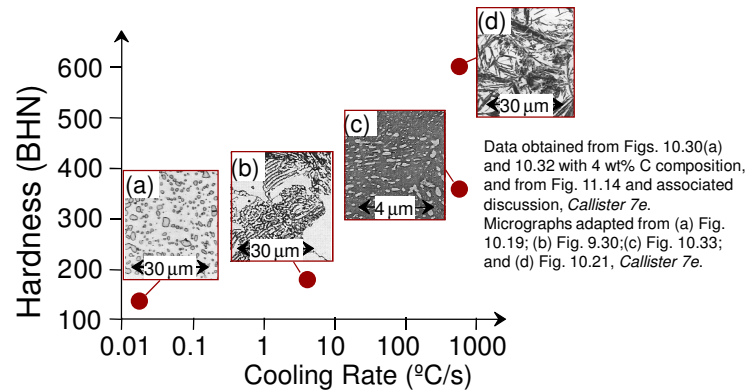
**Structure** will depend on **processing conditions**.

Chapter 1 - 12



## Structure, Processing, & Properties

- **Properties** depend on **structure**  
ex: hardness vs structure of steel



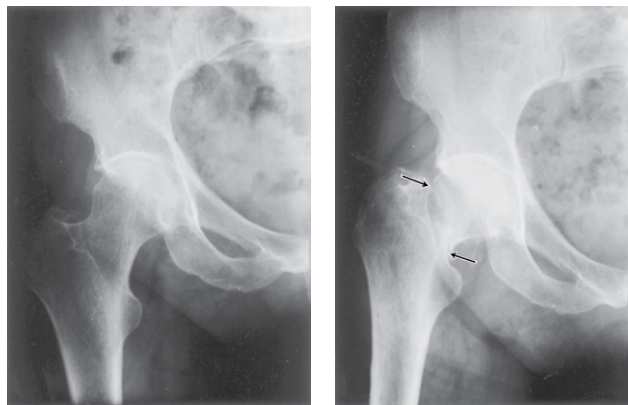
- **Processing** can change **structure**  
ex: structure vs cooling rate of steel

Chapter 1 - 13



## Example – Hip Implant

- With age or certain illnesses joints deteriorate. Particularly those with large loads (such as hip).

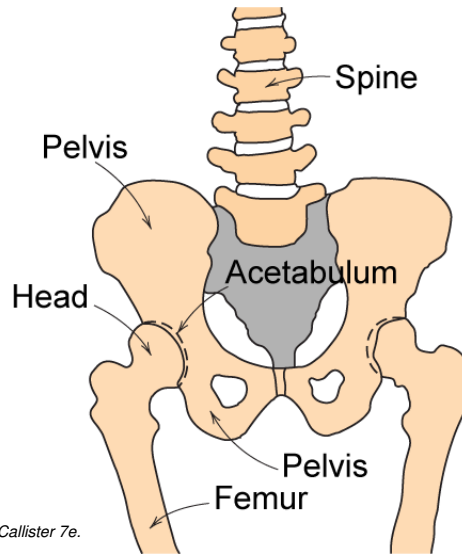
Adapted from Fig. 22.25, *Callister 7e*.

Chapter 1 - 14




## Example – Hip Implant

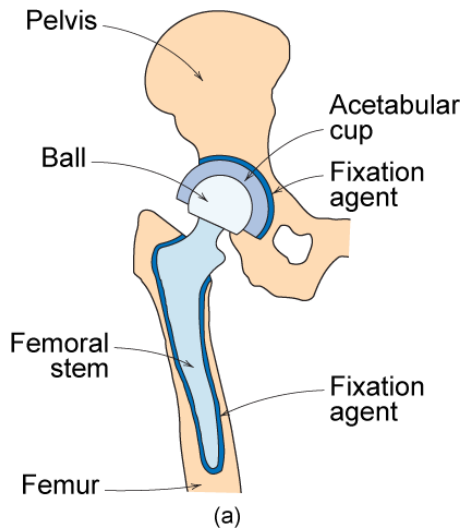
- Requirements
  - mechanical strength (many cycles)
  - good lubricity
  - biocompatibility




Adapted from Fig. 22.24, Callister 7e.

Chapter 1 - 15 

## Example – Hip Implant



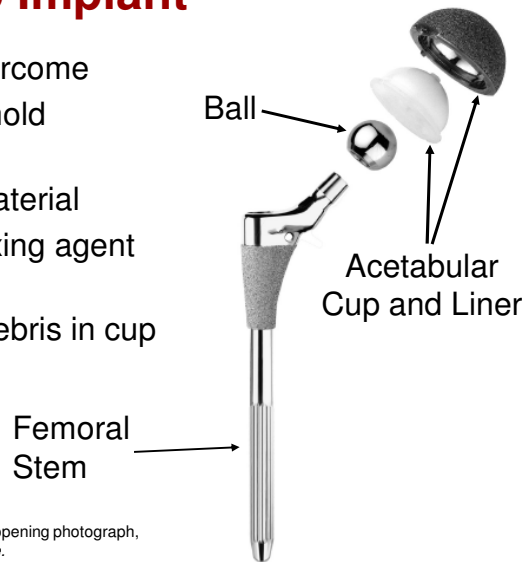
Adapted from Fig. 22.26, Callister 7e.

Chapter 1 - 16 



## Hip Implant

- Key problems to overcome
  - fixation agent to hold acetabular cup
  - cup lubrication material
  - femoral stem – fixing agent (“glue”)
  - must avoid any debris in cup



Adapted from chapter-opening photograph,  
Chapter 22, *Callister 7e*.

Chapter 1 - 17



## Example – Develop New Types of Polymers

- **Commodity plastics** – large volume ca. \$0.50 / lb
  - Ex. Polyethylene
  - Polypropylene
  - Polystyrene
  - etc.
- **Engineering Resins** – small volume > \$1.00 / lb
  - Ex. Polycarbonate
  - Nylon
  - Polysulfone
  - etc.


Can polypropylene be “upgraded” to properties (and price) near those of engineering resins?

Chapter 1 - 18



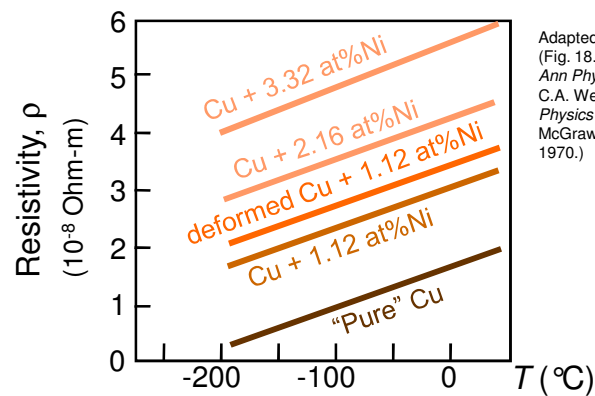
## The Materials Selection Process

1. Pick **Application** → Determine required **Properties**  
Properties: mechanical, electrical, thermal, magnetic, optical, deteriorative.
2. **Properties** → Identify candidate **Material(s)**  
Material: structure, composition.
3. **Material** → Identify required **Processing**  
Processing: changes *structure* and overall *shape*  
ex: casting, sintering, vapor deposition, doping forming, joining, annealing.

Chapter 1 - 19 


## ELECTRICAL

- Electrical Resistivity of Copper:



Adapted from Fig. 18.8, *Callister 7e*.  
(Fig. 18.8 adapted from: J.O. Linde, *Ann Physik* 5, 219 (1932); and C.A. Wert and R.M. Thomson, *Physics of Solids*, 2nd edition, McGraw-Hill Company, New York, 1970.)

- Adding “**impurity**” atoms to Cu increases **resistivity**.
- **Deforming** Cu increases **resistivity**.

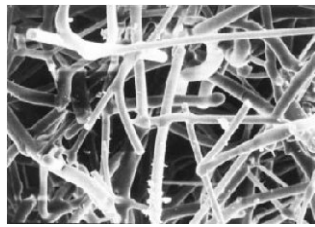
Chapter 1 - 20 

# THERMAL

- Space Shuttle Tiles:
  - Silica fiber insulation offers low heat conduction.



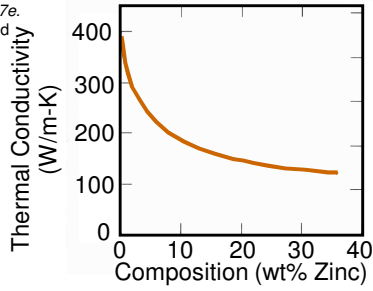
Adapted from chapter-opening photograph, Chapter 19, *Callister 7e*. (Courtesy of Lockheed Missiles and Space Company, Inc.)



Adapted from Fig. 19.4W, *Callister 6e*. (Courtesy of Lockheed Aerospace Ceramics Systems, Sunnyvale, CA) (Note: "W" denotes fig. is on CD-ROM.)

← 100 μm →

- Thermal Conductivity of Copper:
  - It decreases when you add zinc!



Adapted from Fig. 19.4, *Callister 7e*. (Fig. 19.4 is adapted from *Metals Handbook: Properties and Selection: Nonferrous alloys and Pure Metals*, Vol. 2, 9th ed., H. Baker, (Managing Editor), American Society for Metals, 1979, p. 315.)

# MAGNETIC

- Magnetic Storage:
  - Recording medium is magnetized by recording head.
- Magnetic Permeability vs. Composition:
  - Adding 3 atomic % Si makes Fe a better recording medium!

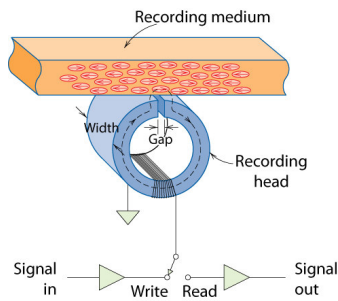
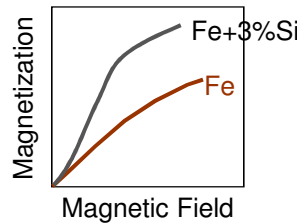


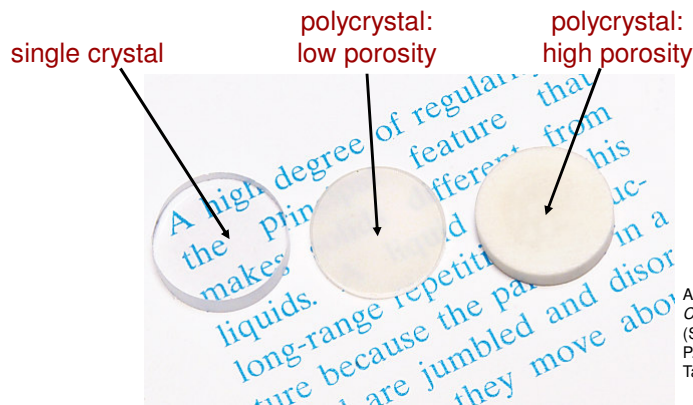
Fig. 20.23, *Callister 7e*. (Fig. 20.23 is from J.U. Lemke, *MRS Bulletin*, Vol. XV, No. 3, p. 31, 1990.)



Adapted from C.R. Barrett, W.D. Nix, and A.S. Tetelman, *The Principles of Engineering Materials*, Fig. 1-7(a), p. 9, 1973. Electronically reproduced by permission of Pearson Education, Inc., Upper Saddle River, New Jersey.

## OPTICAL

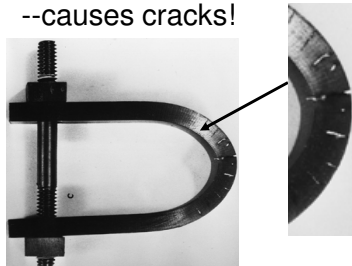
- **Transmittance:**  
 --Aluminum oxide may be transparent, translucent, or opaque depending on the material structure.



Adapted from Fig. 1.2, *Callister 7e*. (Specimen preparation, P.A. Lessing; photo by S. Tanner.)

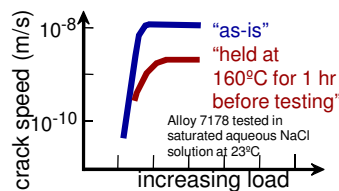
## DETERIORATIVE

- **Stress & Saltwater...**  
 --causes cracks!



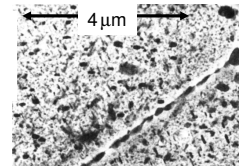
Adapted from chapter-opening photograph, Chapter 17, *Callister 7e*. (from *Marine Corrosion, Causes, and Prevention*, John Wiley and Sons, Inc., 1975.)

- **Heat treatment: slows crack speed in salt water!**



Adapted from Fig. 11.20(b), R.W. Hertzberg, "Deformation and Fracture Mechanics of Engineering Materials" (4th ed.), p. 505, John Wiley and Sons, 1996. (Original source: Markus O. Speidel, Brown Boveri Co.)

- material:  
 7150-T651 Al "alloy"  
 (Zn,Cu,Mg,Zr)



Adapted from Fig. 11.26, *Callister 7e*. (Fig. 11.26 provided courtesy of G.H. Narayanan and A.G. Miller, Boeing Commercial Airplane Company.)

## SUMMARY

### Course Goals:

- Use the right material for the job.
- Understand the relation between **properties**, **structure**, and **processing**.
- Recognize new design opportunities offered by materials selection.